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## Smart Two Channel Highside Power Switch

Features
- Overload protection
- Current limitation
- Short circuit protection
- Thermal shutdown
- Overvoltage protection (including load dump)
- Reverse battery protection[1]
- Undervoltage and overvoltage shutdown with auto-restart and hysteresis
- Open drain diagnostic output
- Open load detection in ON-state
- CMOS compatible input
- Loss of ground and loss of V_{bb} protection
- **E**lectro**s**tatic **d**ischarge (**ESD**) protection

Application
- μC compatible power switch with diagnostic feedback for 12 V DC grounded loads
- Most suitable for resistive and lamp loads

Product Summary

Overvoltage protection	$V_{bb(AZ)}$		43	V
Operating voltage	$V_{bb(on)}$		5.0 ... 24	V
channels:		each	both parallel	
On-state resistance R_{ON}		100	50	mΩ
Load current (ISO) $I_{L(ISO)}$		4.4	8.5	A
Current limitation $I_{L(SCr)}$		10	10	A

TO-220AB/7

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Standard

General Description
N channel vertical power FET with charge pump, ground referenced CMOS compatible input and diagnostic feedback, monolithically integrated in Smart SIPMOS® technology. Fully protected by embedded protection functions.
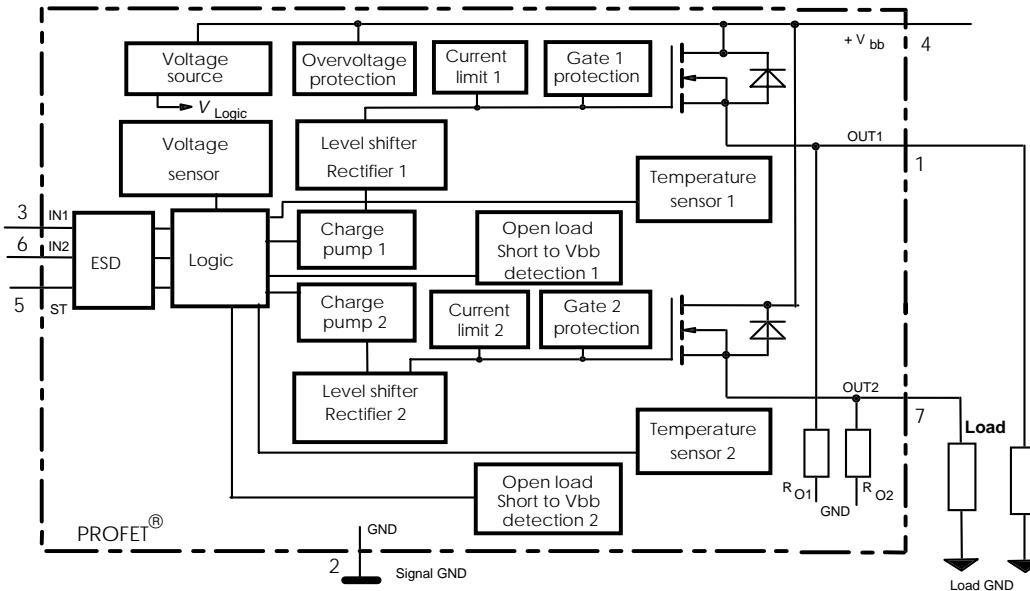
[1] With external current limit (e.g. resistor R_{GND}=150 Ω) in GND connection, resistor in series with ST connection, reverse load current limited by connected load.

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Pin	Symbol	Function
1	OUT1 (Load, L)	Output 1, protected high-side power output of channel 1
2	GND	Logic ground
3	IN1	Input 1, activates channel 1 in case of logical high signal
4	Vbb	Positive power supply voltage, the tab is shorted to this pin
5	ST	Diagnostic feedback: open drain, low on failure
6	IN2	Input 2, activates channel 2 in case of logical high signal
7	OUT2 (Load, L)	Output 2, protected high-side power output of channel 2

Maximum Ratings at T_j = 25 °C unless otherwise specified

Parameter	Symbol	Values	Unit
Supply voltage (overvoltage protection see page 3)	V_{bb}	43	V
Supply voltage for full short circuit protection $T_{j\,Start}$=-40 ...+150°C	V_{bb}	24	V
Load dump protection[2] $V_{LoadDump} = U_A + V_s$, U_A = 13.5 V R_I[3]= 2 Ω, R_L= 2.7 Ω, t_d= 200 ms, IN= low or high	$V_{Load\,dump}$[4]	60	V
Load current (Short circuit current, see page 4)	I_L	self-limited	A
Operating temperature range	T_j	-40 ...+150	°C
Storage temperature range	T_{stg}	-55 ...+150	
Power dissipation (DC), $T_C \leq$ 25 °C	P_{tot}	75	W
Electrostatic discharge capability (ESD) IN: (Human Body Model) all other pins: acc. MIL-STD883D, method 3015.7 and ESD assn. std. S5.1-1993	V_{ESD}	1.0 2.0	kV
Input voltage (DC)	V_{IN}	-10 ... +16	V
Current through input pin (DC)	I_{IN}	±2.0	mA
Current through status pin (DC) see internal circuit diagrams page 6	I_{ST}	±5.0	

Thermal Characteristics

Parameter and Conditions	Symbol	Values			Unit
		min	typ	max	
Thermal resistance chip - case, both channels:	R_{thJC}	--	--	1.7	K/W
each channel:		--	--	3.4	
junction - ambient (free air):	R_{thJA}	--	--	75	

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[2] Supply voltages higher than $V_{bb(AZ)}$ require an external current limit for the GND and status pins, e.g. with a 150 Ω resistor in the GND connection and a 15 kΩ resistor in series with the status pin. A resistor for the protection of the input is integrated.

[3] R_I = internal resistance of the load dump test pulse generator

[4] $V_{Load\,dump}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839

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Electrical Characteristics

Parameter and Conditions, each channel at T_j = 25 °C, V_{bb} = 12 V unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Load Switching Capabilities and Characteristics

Parameter and Conditions	Symbol	min	typ	max	Unit
On-state resistance (pin 4 to 1 or 7) I_L = 2 A $\quad T_j$=25 °C: each channel $\quad T_j$=150 °C:	R_{ON}	--	80 160	100 200	mΩ
Nominal load current, ISO Norm (pin 4 to 1 or 7) V_{ON} = 0.5 V, T_C = 85 °C $\quad$ each channel: both channels parallel:	$I_{L(ISO)}$	3.5 6.8	4.4 8.5	-- --	A
Output current (pin 1 or 7) while GND disconnected or GND pulled up, V_{bb}=30 V, V_{IN}= 0, see diagram page 7	$I_{L(GNDhigh)}$	--	--	10	mA
Turn-on time $\quad$ IN ⎍ to 90% V_{OUT}: Turn-off time $\quad$ IN ⏀ to 10% V_{OUT}: R_L = 12 Ω, T_j =-40...+150°C	t_{on} t_{off}	80 80	200 200	400 400	μs
Slew rate on 10 to 30% V_{OUT}, R_L = 12 Ω, T_j =-40...+150°C	dV /dt_{on}	0.1	--	1	V/μs
Slew rate off 70 to 40% V_{OUT}, R_L = 12 Ω, T_j =-40...+150°C	-dV/dt_{off}	0.1	--	1	V/μs

Operating Parameters

Parameter and Conditions	Symbol	min	typ	max	Unit
Operating voltage [5] $\quad T_j$ =-40...+150°C:	$V_{bb(on)}$	5.0	--	34	V
Operating voltage[6] $\quad T_j$ =-40...+150°C:	$V_{bb(on)}$	5.0	--	24	V
Undervoltage shutdown $\quad T_j$ =-40...+150°C:	$V_{bb(under)}$	3.5	--	5.0	V
Undervoltage restart $\quad T_j$ =-40...+25°C: $\quad T_j$ =+150°C:	$V_{bb(u\,rst)}$	--	--	5.0 7.0	V
Undervoltage restart of charge pump see diagram page 10 $\quad T_j$ =-40...+150°C:	$V_{bb(ucp)}$	--	5.6	7.0	V
Undervoltage hysteresis $\Delta V_{bb(under)}$ = $V_{bb(u\,rst)}$ - $V_{bb(under)}$	$\Delta V_{bb(under)}$	--	0.2	--	V
Overvoltage shutdown $\quad T_j$ =-40...+150°C:	$V_{bb(over)}$	24	--	34	V
Overvoltage restart $\quad T_j$ =-40...+150°C:	$V_{bb(o\,rst)}$	23	--	--	V
Overvoltage hysteresis $\quad T_j$ =-40...+150°C:	$\Delta V_{bb(over)}$	--	0.5	--	V
Overvoltage protection[7] $\quad T_j$ =-40...+150°C: I_{bb}=40 mA	$V_{bb(AZ)}$	42	47	--	V
Standby current (pin 4) V_{IN}=0 $\quad T_j$=-40...+25°C: $\quad T_j$= 150°C:	$I_{bb(off)}$	-- --	14 17	30 35	μA

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[5] At supply voltage increase up to V_{bb}= 5.6 V typ without charge pump, $V_{OUT} \approx V_{bb}$ - 2 V
[6] At supply voltage increase up to V_{bb}= 5.6 V typ without charge pump, $V_{OUT} \approx V_{bb}$ - 2 V
[7] See also $V_{ON(CL)}$ in table of protection functions and circuit diagram page 7.

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Parameter and Conditions, each channel at T_j = 25 °C, V_{bb} = 12 V unless otherwise specified	Symbol	Values			Unit
		min	typ	max	
Leakage output current (included in $I_{bb(off)}$) $V_{IN}=0$	$I_{L(off)}$	--	--	12	μA
Operating current (Pin 2)[8], V_{IN}=5 V both channels on, T_j =-40...+150°C	I_{GND}	--	4	6	mA
Operating current (Pin 2)[8] one channel on, T_j =-40...+150°C:	I_{GND}	--	2	3	mA

Protection Functions

	Symbol	min	typ	max	Unit
Initial peak short circuit current limit (pin 4 to 1 or 7)	$I_{L(SCp)}$				
$\quad T_j$ =-40°C:		16	22	28	A
$\quad T_j$ =25°C:		12	18	24	
$\quad T_j$ =+150°C:		7	11	15	
Repetitive short circuit shutdown current limit $T_j = T_{jt}$ (see timing diagrams, page 9)	$I_{L(SCr)}$	--	10	--	A
Thermal overload trip temperature	T_{jt}	150	--	--	°C
Thermal hysteresis	ΔT_{jt}	--	10	--	K
Reverse battery (pin 4 to 2) [9]	$-V_{bb}$	--	--	32	V
Reverse battery voltage drop ($V_{out} > V_{bb}$) I_L = -2.9 A, each channel $\quad T_j$=150 °C:	$-V_{ON(rev)}$	--	610	--	mV

Diagnostic Characteristics

	Symbol	min	typ	max	Unit
Open load detection current $\quad T_j$=-40 °C: (on-condition,) $\qquad T_j$=25°C: $\qquad T_j$=150°C:	$I_{L(OL)}$	800 800 550	-- -- --	1450 1300 1200	mA
Open load detection voltage[10] (off-condition) $\quad T_j$=-40..150°C:	$V_{OUT(OL)}$	2	3	4	V
Internal output pull down (pin 1 or 7 to 2), V_{OUT}=5 V, T_j=-40..150°C	R_O	4	10	30	kΩ

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[8] Add I_{ST}, if $I_{ST} > 0$, add I_{IN}, if V_{IN}>5.5 V

[9] Requires 150 Ω resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Note that the power dissipation is higher compared to normal operating conditions due to the voltage drop across the intrinsic drain-source diode. The temperature protection is not active during reverse current operation! Input and Status currents have to be limited (see max. ratings page 2 and circuit page 7).

[10] External pull up resistor required for open load detection in off state.

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Parameter and Conditions, each channel	Symbol	Values			Unit
at T_j = 25 °C, V_{bb} = 12 V unless otherwise specified		min	typ	max	

Input and Status Feedback[11]

Parameter and Conditions	Symbol	min	typ	max	Unit
Input resistance T_j=-40..150°C, see circuit page 6	R_I	2.5	3.5	6	kΩ
Input turn-on threshold voltage ⌐ T_j =-40..+150°C:	$V_{IN(T+)}$	1.7	--	3.5	V
Input turn-off threshold voltage ⌐ T_j =-40..+150°C:	$V_{IN(T-)}$	1.5	--	--	V
Input threshold hysteresis	$\Delta V_{IN(T)}$	--	0.5	--	V
Off state input current (pin 3 or 6), V_{IN} = 0.4 V, T_j =-40..+150°C	$I_{IN(off)}$	1	--	50	μA
On state input current (pin 3 or 6), V_{IN} = 3.5 V, T_j =-40..+150°C	$I_{IN(on)}$	20	50	90	μA
Delay time for status with open load after switch off (other channel in off state) (see timing diagrams, page 10), T_j =-40..+150°C	$t_{d(ST\,OL4)}$	100	320	800	μs
Delay time for status with open load after switch off (other channel in on state) (see timing diagrams, page 10), T_j =-40..+150°C	$t_{d(ST\,OL5)}$	--	5	20	μs
Status invalid after positive input slope (open load) T_j=-40 ... +150°C:	$t_{d(ST)}$	--	200	600	μs
Status output (open drain) Zener limit voltage T_j =-40...+150°C, I_{ST} = +1.6 mA:	$V_{ST(high)}$	5.4	6.1	--	V
ST low voltage T_j =-40...+25°C, I_{ST} = +1.6 mA:	$V_{ST(low)}$	--	--	0.4	
T_j = +150°C, I_{ST} = +1.6 mA:		--	--	0.6	

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[11] If a ground resistor R_{GND} is used, add the voltage drop across this resistor.

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Truth Table

		IN1	IN2	OUT1	OUT2	ST BTS620L1 BTS621L1
Normal operation		L	L	L	L	H
		L	H	L	H	H
		H	L	H	L	H
		H	H	H	H	H
Open load	Channel 1	L	L	Z	L	H(L[12])
		L	H	Z	H	H
		H	X	H	X	L
	Channel 2	L	L	L	Z	H(L[12])
		H	L	H	Z	H
		X	H	X	H	L
Short circuit to V_{bb}	Channel 1	L	L	H	L	L[13]
		L	H	H	H	H
		H	X	H	X	H(L[14])
	Channel 2	L	L	L	H	L[13]
		H	L	H	H	H
		X	H	X	H	H(L[14])
Overtemperature	both channel	L	L	L	L	H
		X	H	L	L	L
		H	X	L	L	L
	Channel 1	L	X	L	X	H
		H	X	L	X	L
	Channel 2	X	L	X	L	H
		X	H	X	L	L
Undervoltage/ Overvoltage		X	X	L	L	H

L = "Low" Level   X = don't care   Z = high impedance, potential depends on external circuit
H = "High" Level   Status signal after the time delay shown in the diagrams (see fig 5. page 10)

Terms
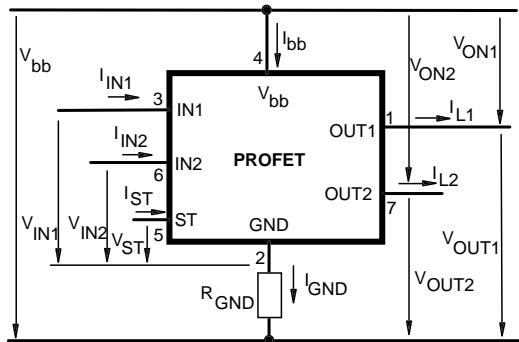
Input circuit (ESD protection)
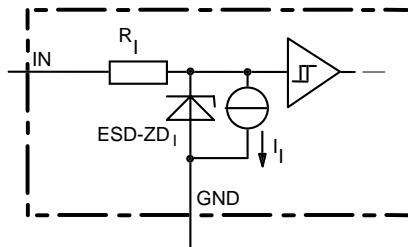
ESD zener diodes are not to be used as voltage clamp at DC conditions. Operation in this mode may result in a drift of the zener voltage (increase of up to 1 V).

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[12] With additional external pull up resistor

[13] An external short of output to V_{bb}, in the off state, causes an internal current from output to ground. If R_{GND} is used, an offset voltage at the GND and ST pins will occur and the $V_{ST\ low}$ signal may be errorious.

[14] Low resistance to V_{bb} may be detected in the ON-state by the no-load-detection

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Status output
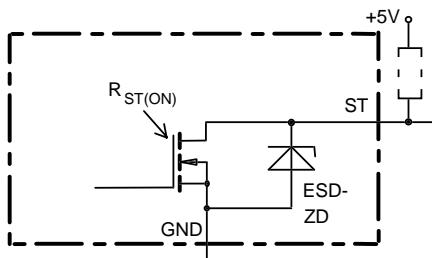
ESD-Zener diode: 6.1 V typ., max 5 mA;
$R_{ST(ON)}$ < 380 Ω at 1.6 mA, ESD zener diodes are not to be used as voltage clamp at DC conditions.
Operation in this mode may result in a drift of the zener voltage (increase of up to 1 V).

## overvoltage output clamp
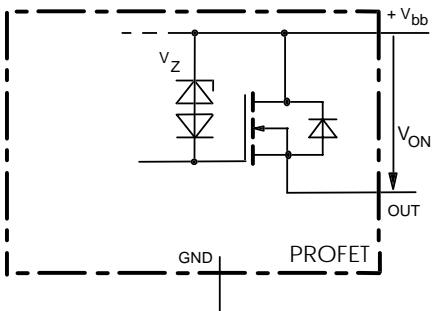
V_{ON} clamped to 47 V typ.

Overvolt. and reverse batt. protection
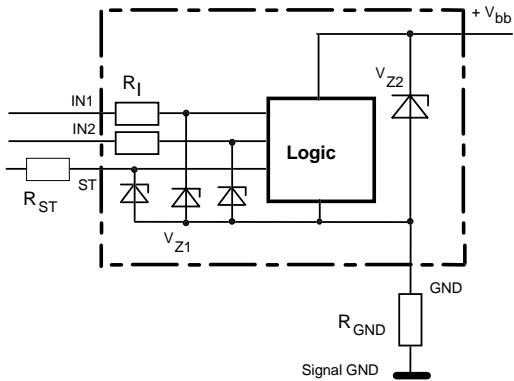
V_{Z1} = 6.1 V typ., V_{Z2} = 47 V typ., R_I= 3.5 kΩ typ, R_{GND}= 150 Ω

Open-load detection

ON-state diagnostic condition: $V_{ON} < R_{ON} * I_{L(OL)}$; IN high
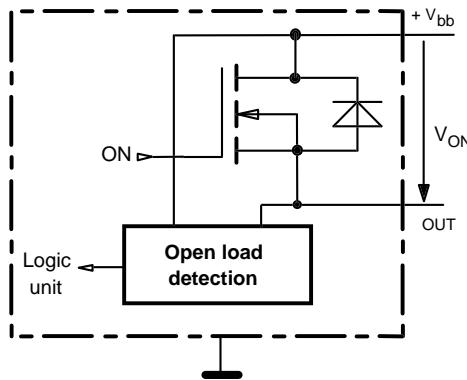
OFF-state diagnostic condition: V_{OUT} > 3 V typ.; IN low
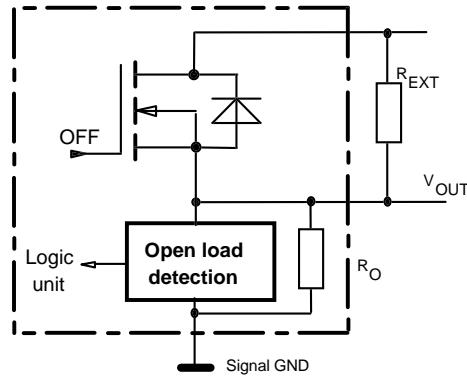
GND disconnect
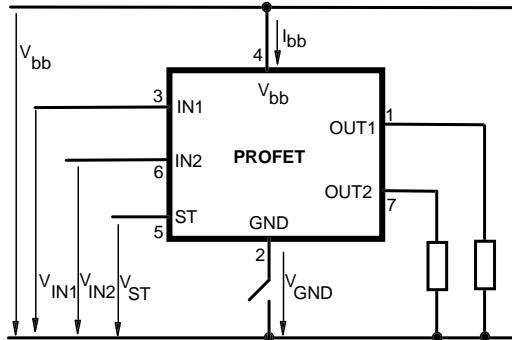
In case of Input=high is $V_{OUT} \approx V_{IN} - V_{IN(T+)}$.
Due to V_{GND} >0, no V_{ST} = low signal available.

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GND disconnect with GND pull up
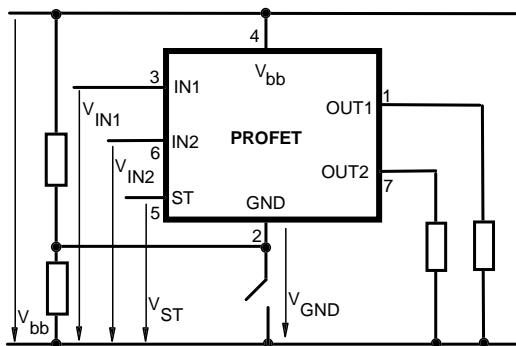
If $V_{GND} > V_{IN} - V_{IN(T+)}$ device stays off
Due to $V_{GND} > 0$, no V_{ST} = low signal available.

Typ. transient thermal impedance chip case
$Z_{thJC} = f(t_p)$, one Channel active

Z_{thJC} [K/W]
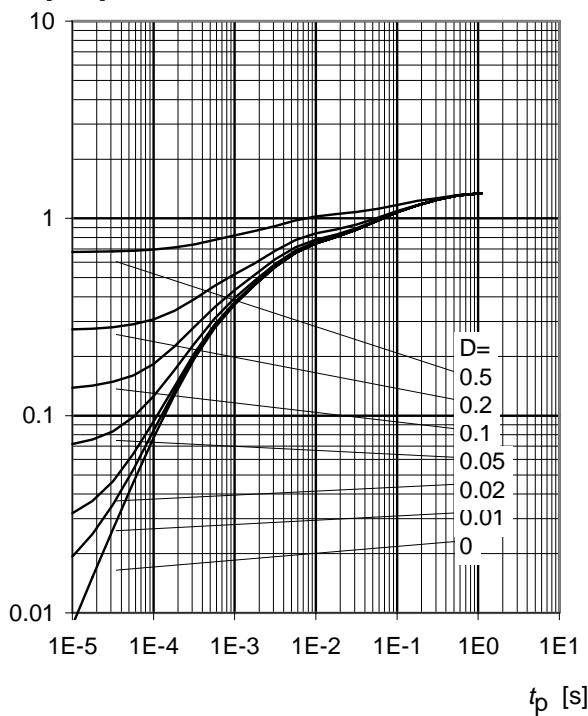
Typ. transient thermal impedance chip case
$Z_{thJC} = f(t_p)$, both Channel active

Z_{thJC} [K/W]

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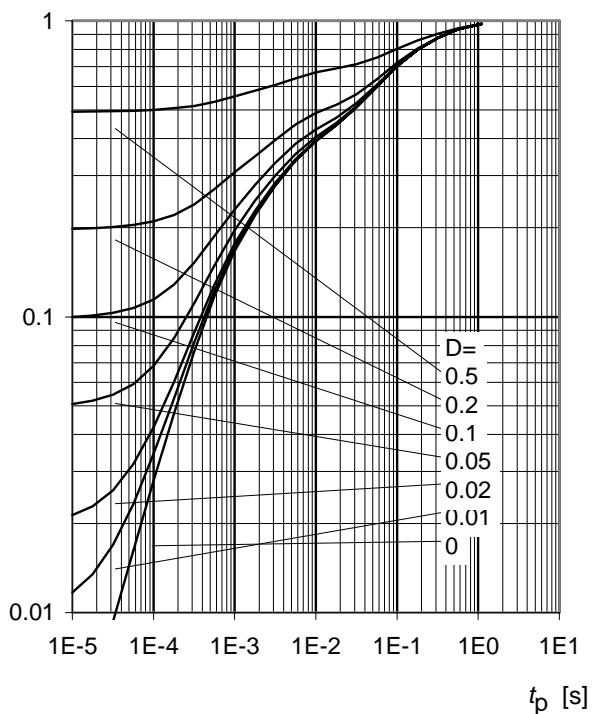
Timing diagrams

Both channels are symmetric and consequently the diagrams are valid for each channel as well as for permuted channels

Figure 1a: V_{bb} turn on:

IN1

IN2

V_{bb}

V_{OUT1}

V_{OUT2}

ST open drain

t
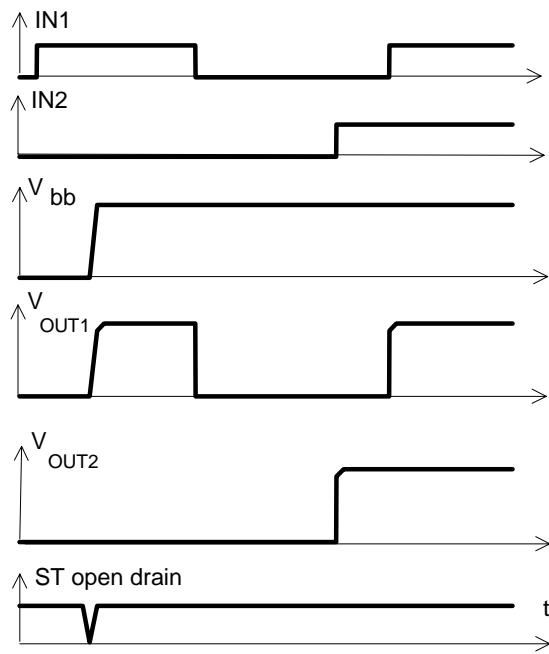
Figure 2a: Switching a lamp:

IN

ST

V_{OUT}

I_L

t
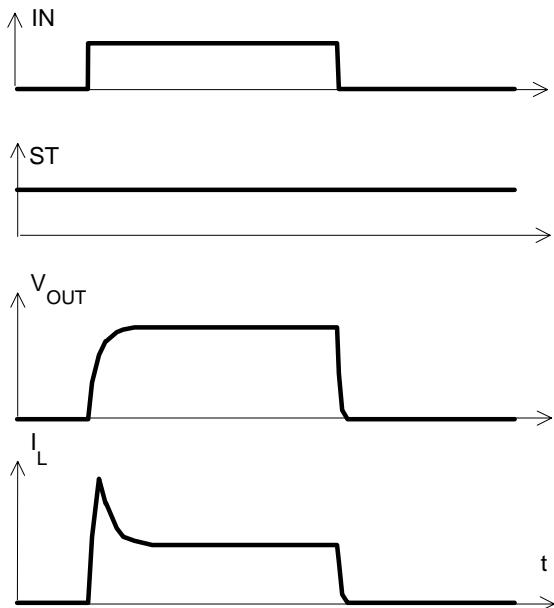
Figure 3a: Short circuit
shut down by overtempertature, reset by cooling

IN   other channel: normal operation

I_L

$I_{L(SCp)}$ $I_{L(SCr)}$

ST

t
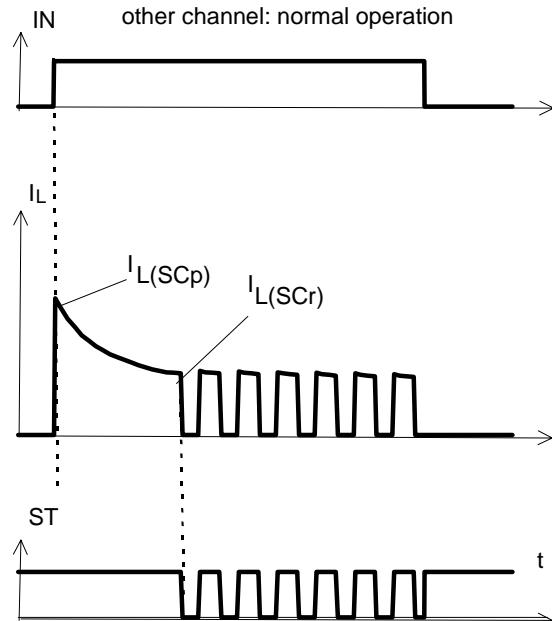
Heating up may require several milliseconds, depending on external conditions

Figure 4a: Overtemperature:
Reset if $T_j < T_{jt}$

IN

ST

V_{OUT}

T_J

t

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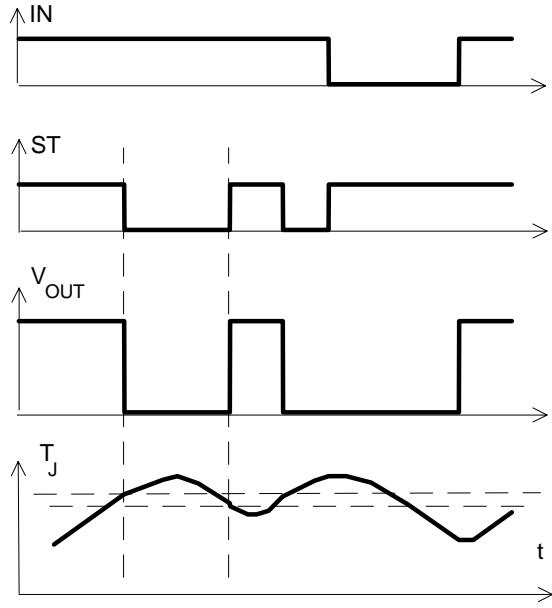
Figure 5a: Open load: detection in ON-state, open load occurs in on-state
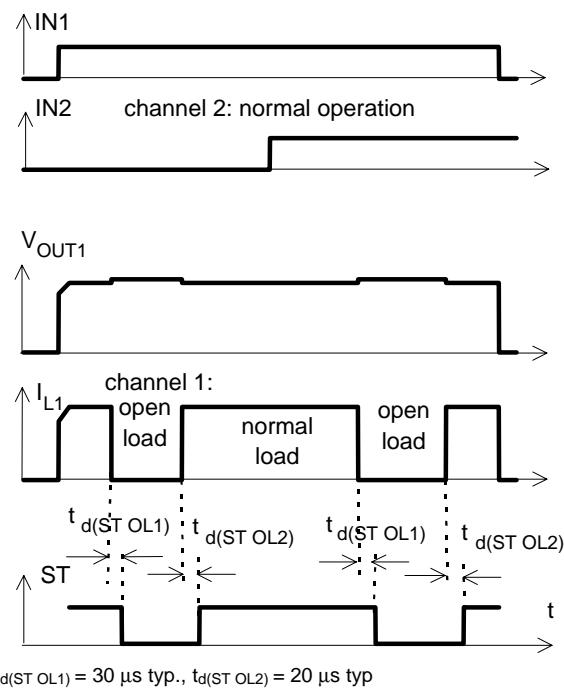
$t_{d(ST\ OL1)} = 30\ \mu s$ typ., $t_{d(ST\ OL2)} = 20\ \mu s$ typ

Figure 5b: Open load: detection in ON-state, turn on/off to open load
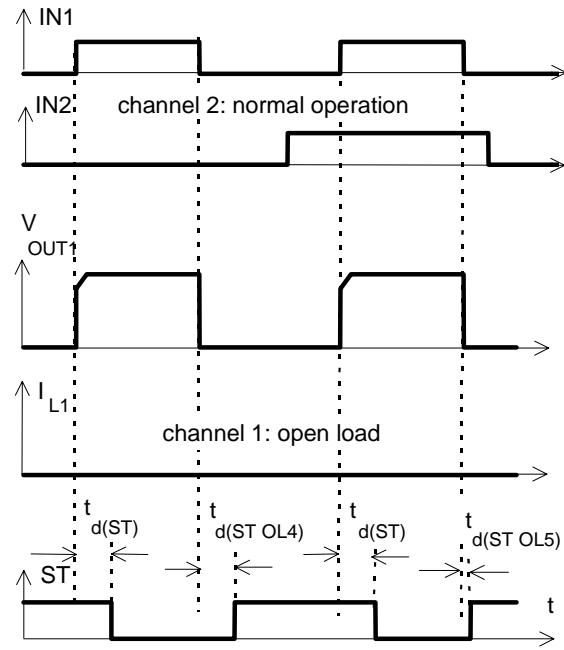
**Figure 5c:** Open load: detection in ON- and OFF-state (with R_{EXT}), turn on/off to open load

$t_{d(ST\ OL5)}$ depends on external circuitry because of high impedance
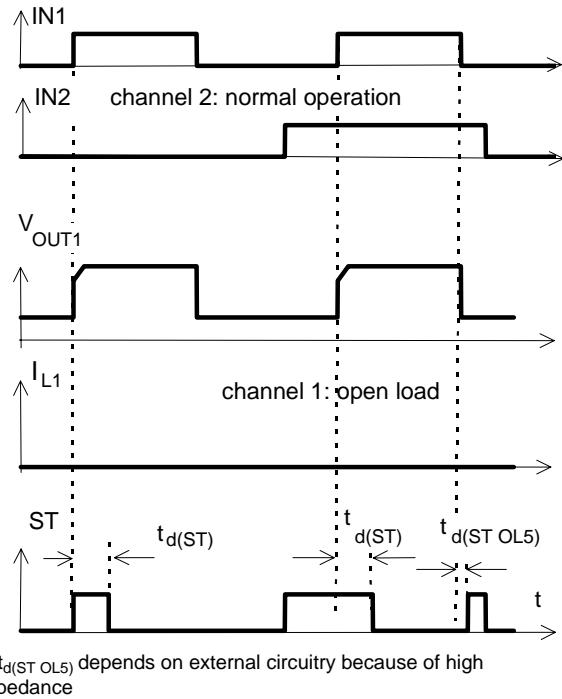
Figure 6a: Undervoltage:

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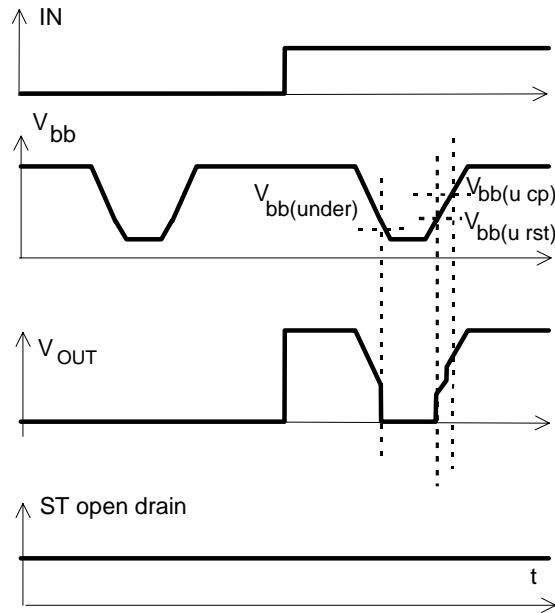
Figure 6b: Undervoltage restart of charge pump

charge pump starts at $V_{bb(ucp)}$ =5.6 V typ.
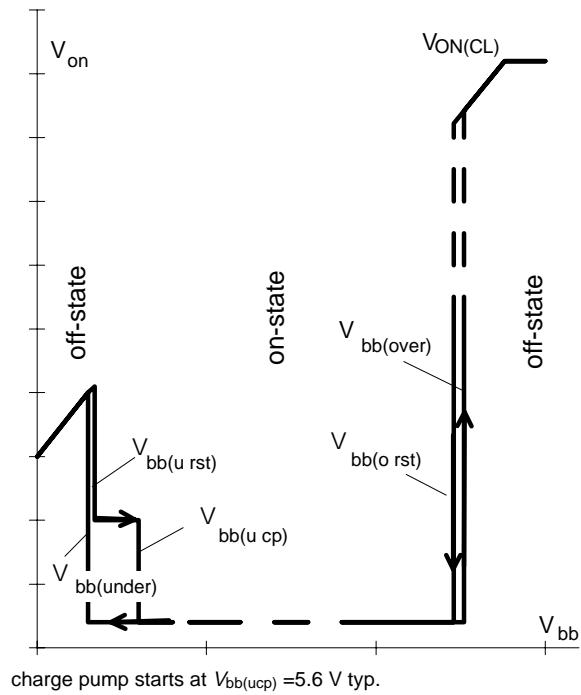
Figure 7a: Overvoltage:
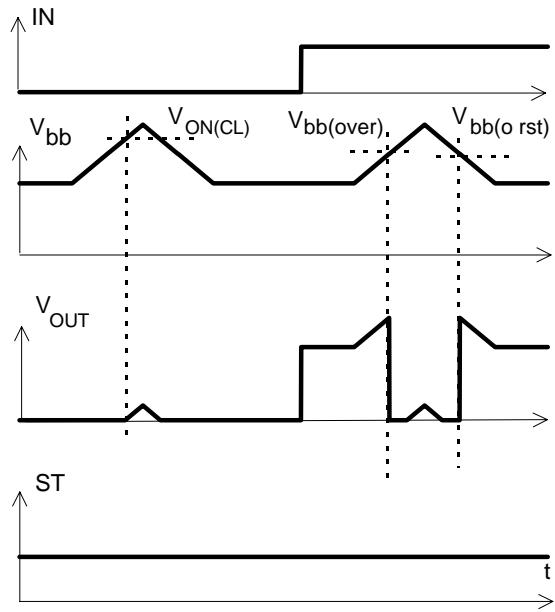
Package and Ordering Code

All dimensions in mm

Standard TO-220AB/7   Ordering code

BTS620L1	Q67060-S6301-A2

1) shear and punch direction no burrs this surface

GPT05167
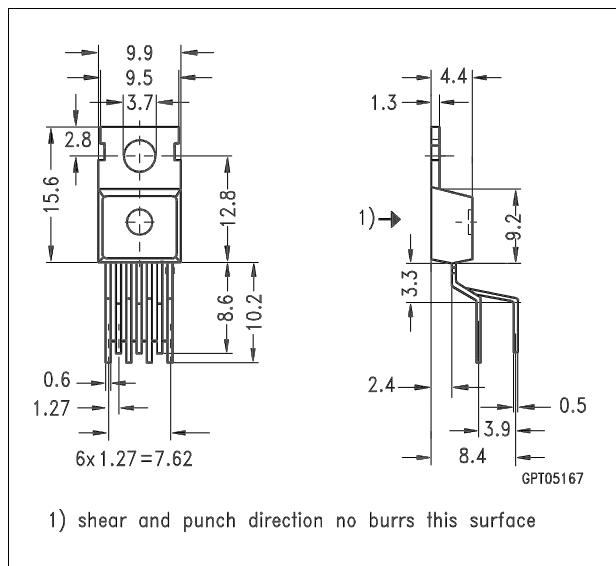
Changed since 04.96

Date	Change
Dec 1996	td(ST OL4) max reduced from 1500 to 800µs, typical from 400 to 320µs, min limit unchanged
	Zth specification added
	max Output leakage current IL(off) reduced from 20 to 12 µA
	increased ESD capability
	Typ. reverse battery voltage drop - $V_{ON(rev)}$ added